



# SLOVENSKI STANDARD

## SIST EN 62047-18:2014

01-maj-2014

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### Polprevodniški elementi - Mikroelektromehanski elementi - 18. del: Metode za upogibno preskušanje tankoplastnih materialov (IEC 62047-18:2013)

Semiconductor devices - Micro-electromechanical devices - Part 18: Bend testing methods of thin film materials

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## iTeh STANDARD PREVIEW

Dispositifs à semiconducteurs - Dispositif microélectromécaniques - Partie 18: Méthodes d'essai de flexion des matériaux en couche mince

[SIST EN 62047-18:2014](https://standards.itih.ai/catalog/standards/sist/56ea0098-1d4a-4140-8108-9c4510b20649/sist-en-62047-18-2014)

Ta slovenski standard je istoveten z: **EN 62047-18:2013**

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#### **ICS:**

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
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**SIST EN 62047-18:2014**

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EUROPEAN STANDARD  
NORME EUROPÉENNE  
EUROPÄISCHE NORM

**EN 62047-18**

September 2013

ICS 31.080.99

English version

**Semiconductor devices -  
Micro-electromechanical devices -  
Part 18: Bend testing methods of thin film materials  
(IEC 62047-18:2013)**

Dispositifs à semiconducteurs -  
Dispositif microélectromécaniques -  
Partie 18: Méthodes d'essai de flexion des  
matériaux en couche mince  
(CEI 62047-18:2013)

Halbleiterbauelemente -  
Bauelemente der Mikrosystemtechnik -  
Teil 18: Biegeprüfverfahren für  
Dünnschichtwerkstoffe  
(IEC 62047-18:2013)

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**CEN-CENELEC Management Centre: Avenue Marnix 17, B - 1000 Brussels**

## Foreword

The text of document 47F/155/FDIS, future edition 1 of IEC 62047-18, prepared by SC 47F "Microelectromechanical systems" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62047-18:2013.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2014-05-21
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2016-08-21

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62047-6	2009	Semiconductor devices - Micro-electromechanical devices - Part 6: Axial fatigue testing methods of thin film materials	EN 62047-6	2010

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IEC 62047-18

Edition 1.0 2013-07

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Semiconductor devices – Micro-electromechanical devices –  
Part 18: Bend testing methods of thin film materials**

**Dispositifs à semiconducteurs – Dispositifs microélectromécaniques –  
Partie 18: Méthodes d'essai de flexion des matériaux en couche mince**

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## CONTENTS

FOREWORD.....	3
1 Scope.....	5
2 Normative references .....	5
3 Symbols and designations .....	6
4 Test piece .....	6
4.1 Design of test piece.....	6
4.2 Preparation of test piece .....	7
4.3 Test piece width and thickness .....	7
4.4 Storage prior to testing .....	7
5 Testing method.....	7
5.1 General .....	7
5.2 Method for mounting of test piece.....	9
5.3 Method for loading.....	9
5.4 Speed of testing .....	9
5.5 Displacement measurement .....	9
5.6 Test environment.....	9
5.7 Data analysis .....	9
5.8 Material for test pieces .....	10
6 Test report.....	10
Annex A (informative) Precautions for the test piece-substrate interface .....	11
Annex B (informative) Precautions necessary for the force displacement relationship .....	12
Figure 1 – Schematically shown test piece with substrate.....	6
Figure 2 – Measurement method.....	8
Figure A.1 – Finishing angle of substrate contact area with test piece.....	11
Figure B.1 – Cantilever type bend test piece of metallic glass in accordance with IEC 62047-18.....	12
Figure B.2 – Typical example of relationship between force and displacement.....	13
Table 1 – Symbols and designation of test piece.....	6

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**SEMICONDUCTOR DEVICES –  
MICRO-ELECTROMECHANICAL DEVICES –**
**Part 18: Bend testing methods of thin film materials****FOREWORD**

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International Standard IEC 62047-18 has been prepared by subcommittee 47F: Micro-electromechanical systems, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47F/155/FDIS	47F/162/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62047 series, published under the general title *Semiconductor devices – Micro-electromechanical devices*, can be found on the IEC website.